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CONSOLIDATED VERSION

Surface mounted piezoelectric devices for frequency control and selection - Standard outlines and terminal lead connections - Part 2: Ceramic enclosures

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

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FOREWORD

1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
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This consolidated version of the official IEC Standard and its amendments has been prepared for user convenience.

IEC 61837-2 edition 3.2 contains the third edition (2018-05) [documents 49/1252/CDV and 49/1276/RVC], its amendment 1 (2020-09) [documents 49/1338/CDV and 49/1347/RVC] and its amendment 2 (2026-06) [documents 49/1523/CDV and 49/1534/RVC].

In this Redline version, a vertical line in the margin shows where the technical content is modified by amendments 1 and 2. Additions are in green text, deletions are in strikethrough red text. A separate Final version with all changes accepted is available in this publication.

International Standard IEC 61837-2 has been prepared by IEC technical committee 49: Piezoelectric, dielectric and electrostatic devices and associated materials for frequency control, selection and detection.

This third edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

a) revision of the figures to match the notation of the drawings of IEC 61240:2016;
b) addition of 7 enclosures as follows: DCC-6/5032A, DCC-6/3225A, DCC-4/3215C, DCC-6/2016A, DCC-2/2012C, DCC-2/1610C, DCC-4/1210C.

As a result, this third edition contains a total of 45 enclosure types, which are listed in Table 1.

This International Standard is to be read in conjunction with IEC 61240:2016.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 61837 series, published under the general title *Surface mounted piezoelectric devices for frequency control and selection – Standard outlines and terminal lead connections* , can be found on the IEC website.

The committee has decided that the contents of this document and its amendments will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

– reconfirmed,
– withdrawn, or
– revised.

1 Scope

This part of IEC 61837 deals with standard outlines and terminal lead connections as they apply to surface-mounted devices (SMD) for frequency control and selection in ceramic enclosures, and is based on IEC 61240:2016.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61240:2016, *Piezoelectric devices – Preparation of outline drawings of surface-mounted devices (SMD) for frequency control and selection – General rules*

3 Terms and definitions

No terms and definitions are listed in this document.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at http://www.electropedia.org/
- ISO Online browsing platform: available at http://www.iso.org/obp

4 Configuration of enclosures

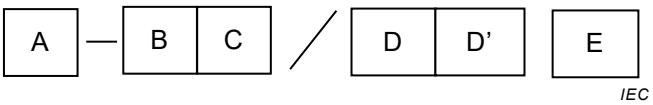
The enclosures of the surface-mounted devices are made of ceramic materials with the terminals of deposited metal film (leadless type) based on a descriptive designation system for semiconductors – devices packages.

The configuration symbols are shown as follows:

- DCC (dual chip carrier);
- QCC (quad chip carrier).

5 Designation of types

The designation of types is shown on four parts as follows:



A: Configuration symbol of enclosures:
  – DCC (dual chip carrier);
  – QCC (quad chip carrier).

B: Structure of terminal leads: leadless type has no mark.

C: Number of terminal leads

D: Serial number of both figures

E: Arrangement of terminal land:

In the case of DCC types:

– A (arrangement in the width direction side or the width direction side and the corner);
– B (arrangement in the length direction side or the length direction side and the corner);
– C (arrangement in the corner only).

In the case of QCC types:

– A (arrangement in the side only);
– B (arrangement in the side and the corner).

6 Ceramic enclosure dimensions

The dimensions given in this document apply to all completed SMD-devices for frequency control and selection. Only those dimensions which meet the requirements of IEC 61240 are given.

7 Lead connections

Recommendations for the lead connections of all completed SMD-devices for frequency control and selection are given in the following individual sheets. Lead connections shall always be given in the detail specification.

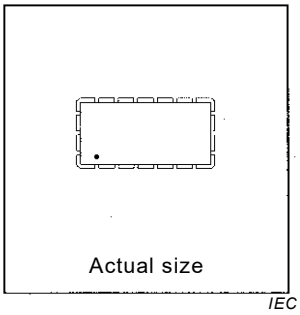
8 Designation of ceramic enclosures

Table 1 is a list which includes all new enclosure types with their sheet numbers and brief descriptions. Old enclosure names are also listed as references.

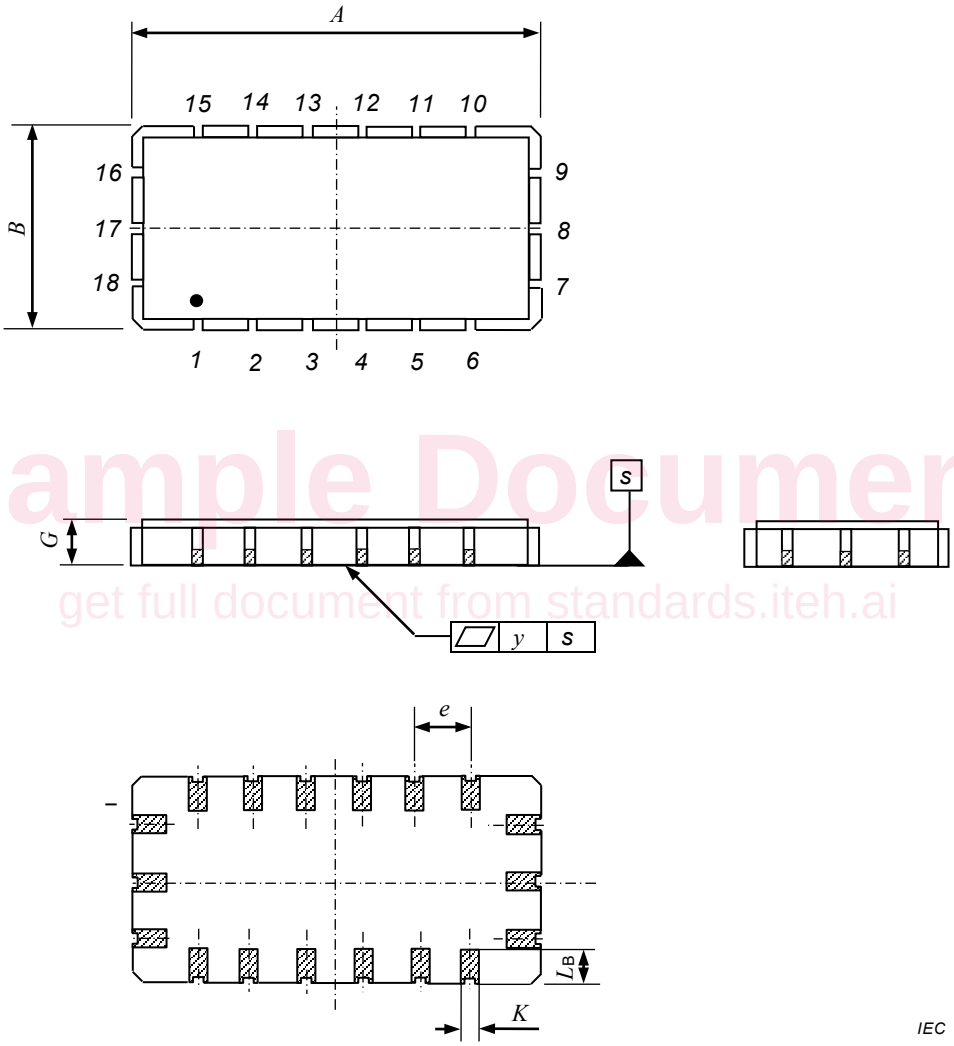
Table 1 – Designation of ceramic enclosures

No.	Type	Old type	Sheet No.	Description
1	QCC-18/1809A	QCC-18/01	Sheet 1	Ceramic, welded, eighteen leadless SMD outline
2	QCC-12/1407A		Sheet 2	Ceramic, welded, twelve leadless SMD outline
3	DCC-4/1206A	DCC-4/01	Sheet 3	Ceramic, four leadless SMD outline
4	DCC-2/1206A		Sheet 4	Ceramic, two leadless SMD outline
5	QCC-10/9272A		Sheet 5	Ceramic, welded, ten leadless SMD outline
6	DCC-4/9070A		Sheet 6	Ceramic, welded, four leadless SMD outline
7	DCC-4/8045B	DCC-04/02, 03	Sheet 7	Ceramic, welded, four leadless SMD outline
8	DCC-2/8045B		Sheet 8	Ceramic, welded, two leadless SMD outline
9	DCC-6/7834B		Sheet 9	Ceramic, welded, six leadless SMD outline
10	DCC-6/7050A		Sheet 10	Ceramic, welded, six leadless SMD outline
11	DCC-4/7050A	DCC-4/08	Sheet 11	Ceramic, welded, four leadless SMD outline
12	DCC-4/7050B	DCC-4/04, 05	Sheet 12	Ceramic, welded, four leadless SMD outline
13	QCC-10/7050A		Sheet 13	Ceramic, welded, ten leadless SMD outline
14	QCC-6/7050A	QCC-6/01, 02	Sheet 14	Ceramic, welded, six leadless SMD outline
15	DCC-6/6035A	DCC-4/06, 07	Sheet 15	Ceramic, welded, six leadless SMD outline
16	DCC-4/6035C		Sheet 16	Ceramic, welded, four leadless SMD outline
17	DCC-2/6035C		Sheet 17	Ceramic, welded, two leadless SMD outline
18	QCC-8/5050A	QCC-8/02	Sheet 18	Ceramic, welded, eight leadless SMD outline
19	QCC-12/5045A	QCC-12/02	Sheet 19	Ceramic, welded, twelve leadless SMD outline
20	QCC-8/5045A		Sheet 20	Ceramic, welded, eight leadless SMD outline
21	DCC-6/5032A		Sheet 21	Ceramic, welded, six leadless SMD outline
22	DCC-4/5032A		Sheet 22	Ceramic, welded, four leadless SMD outline
23	DCC-4/5032C		Sheet 23	Ceramic, welded, four leadless SMD outline
24	DCC-2/5032B	DCC-2/01	Sheet 24	Ceramic, welded, two leadless SMD outline
25	DCC-2/4818C		Sheet 25	Ceramic, welded, two leadless SMD outline
26	DCC-2/4115C		Sheet 26	Ceramic, welded, two leadless SMD outline
27	DCC-4/4025C	DCC-6/01	Sheet 27	Ceramic, welded, four leadless SMD outline
28	QCC-8/3838A		Sheet 28	Ceramic, welded, eight leadless SMD outline
29	DCC-6/3838A		Sheet 29	Ceramic, welded, six leadless SMD outline
30	DCC-6/3225A		Sheet 30	Ceramic, welded, six leadless SMD outline
31	DCC-4/3225C		Sheet 31	Ceramic, welded, four leadless SMD outline
32	DCC-4/3215C		Sheet 32	Ceramic, welded, four leadless SMD outline
33	DCC-2/3215C		Sheet 33	Ceramic, welded, two leadless SMD outline
34	QCC-8/3030B		Sheet 34	Ceramic, welded, eight leadless SMD outline
35	DCC-6/3030A		Sheet 35	Ceramic, welded, six leadless SMD outline
36	DCC-6/2520A		Sheet 36	Ceramic, welded, six leadless SMD outline
37	DCC-4/2520C/01,02,03		Sheet 37	Ceramic, welded, four leadless SMD outline
38	DCC-4/2020C		Sheet 38	Ceramic, welded, ~~six~~ four leadless SMD outline
39	DCC-6/2016A		Sheet 39	Ceramic, welded, ~~four~~ six leadless SMD outline
40	DCC-4/2016C/01,02,03		Sheet 40	Ceramic, welded, four leadless SMD outline
41	DCC-2/2012C		Sheet 41	Ceramic, welded, two leadless SMD outline
42	DCC-4/1612C/01,02		Sheet 42	Ceramic, welded, four leadless SMD outline
43	DCC-2/1612C		Sheet 43	Ceramic, welded, two leadless SMD outline
44	DCC-2/1610C		Sheet 44	Ceramic, welded, two leadless SMD outline
45	DCC-4/1210C/01,02		Sheet 45	Ceramic, welded, four leadless SMD outline

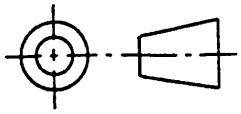
No.	Type	Old type	Sheet No.	Description
46	DCC-8/3225A		Sheet 46	Ceramic, welded, eight leadless SMD outline
47	DCC-4/1008C/0,1,02		Sheet 47	Ceramic, welded, four leadless SMD outline
48	DCC-4/0806C		Sheet 48	Ceramic, welded, four leadless SMD outline



Ref.	Dimensions (mm)			Notes
	Min.	Nom.	Max.	
A	–	(18,0)	18,30	
B	–	(9,0)	9,30	
G	–	–	2,00	
K	0,50	–	1,10	
L_B	1,20	–	1,80	Note
e	–	2,54	–	
y	–	–	0,10	

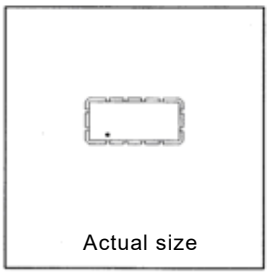


NOTE Dimension L_B max. can be increased to 2,10 mm for lead 1 to identity the orientation.

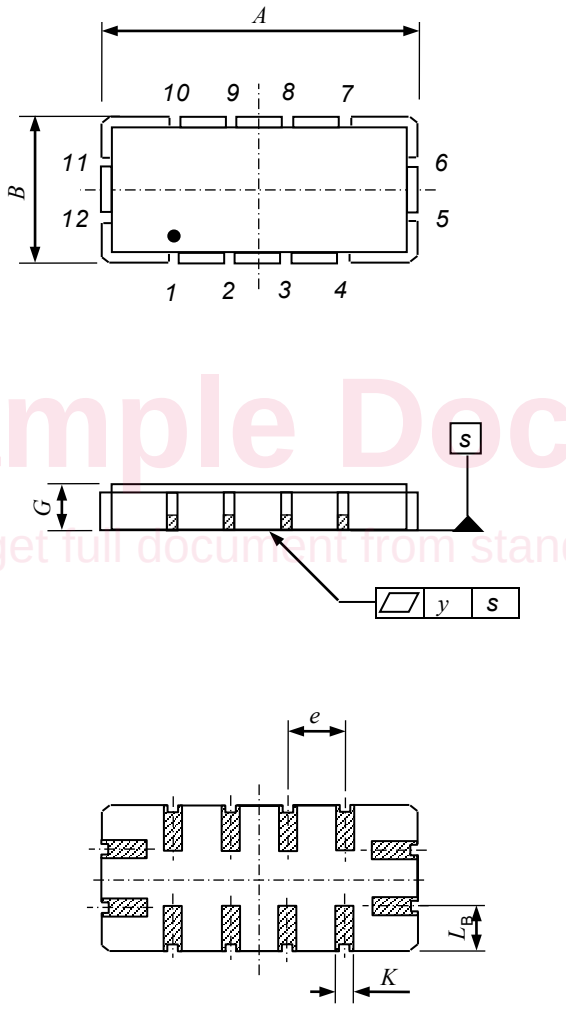
Ceramic, welded, eighteen leadless SMD outline – Type QCC-18/1809A	Scale 3: 1	
Sheet 1		

Terminal land connections of Type QCC-18/1809A

No.	Crystal unit	Crystal oscillator	Crystal filter	SAW devices
1				Ground
2				Option
3				Option
4				Option
5				Option
6				Ground
7				Input/Output
8				Ground
9				Input/Output /Ground
10				Ground
11				Option
12				Option
13				Option
14				Option
15				Ground
16				Output/Input
17				Ground
18				Output/Input /Ground



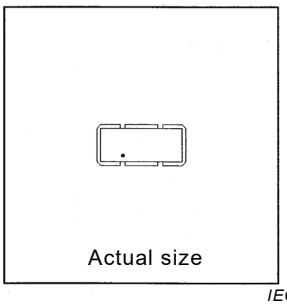
Ref.	Dimensions (mm)			Notes
	Min.	Nom.	Max.	
A	–	(14,0)	14,30	
B	–	(6,5)	6,80	
G	–	–	2,00	
K	0,50	–	1,10	
L_B	1,70	–	2,30	
e	–	2,54	–	
y	–	–	0,10	



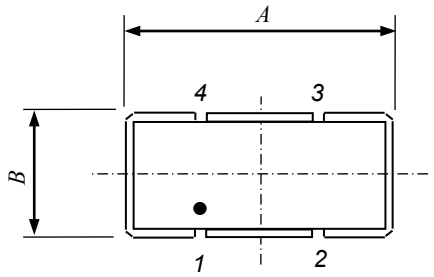
Ceramic, welded, twelve leadless SMD outline – Type QCC-12/1407A	Scale 3: 1	
Sheet 2		

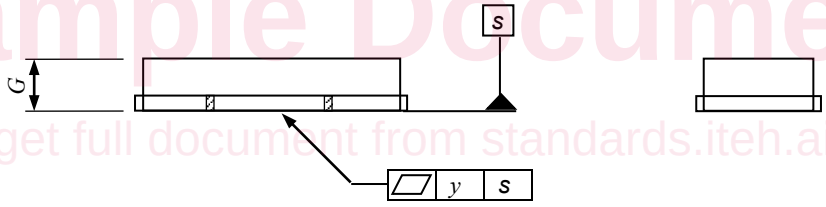
Terminal land connections of Type QCC-12/1407A

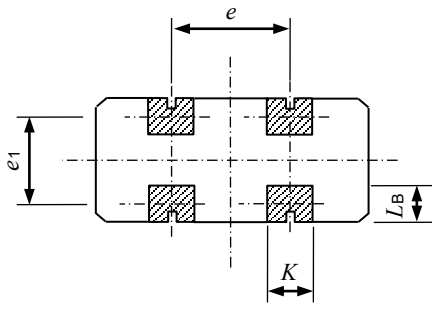
No.	Crystal unit	Crystal oscillator	Crystal filter	SAW devices
1				Option
2				Option
3				Ground
4				Option
5				Output/Input
6				Output/Input /Ground
7				Option
8				Ground
9				Option
10				Option
11				Input/Output
12				Input/Output /Ground



Ref.	Dimensions (mm)			Notes
	Min.	Nom.	Max.	
A	–	(12,0)	12,30	
B	–	(5,5)	5,80	
G	–	–	2,30	
K	1,80	–	2,20	
L_B	1,30	–	1,90	
e	–	5,08	–	
e_1	–	3,90	–	
y	–	–	0,10	







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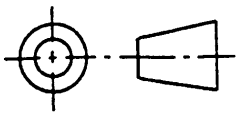
Ceramic, welded, four leadless SMD outline – Type DCC-4/1206A	Scale 3: 1	
Sheet 3		